

Electrostatic Discharged Protection Devices (ESD) Data Sheet

Description

The SDD52A12L01 is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, portable devices, digital cameras, power supplies and many other portable applications. It is designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge(ESD), electrical fast transients(EFT), and cable discharge events(CDE).



Contact : ±30kV
Air : ±30kV

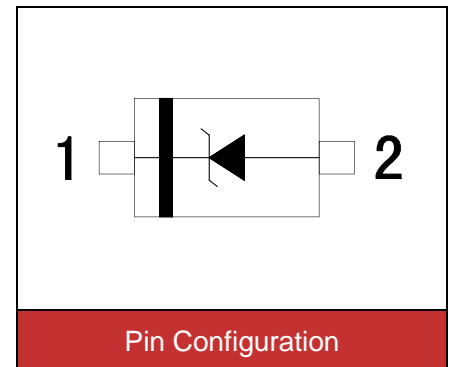


Features

- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- SOD-523 surface mount package
- Working voltage: 12V
- Low leakage current
- Lead Free/RoHS compliant
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: 12A

Applications

- Cellular handsets & Accessories
- Cordless phones
- Personal digital assistants (PDAs)
- Notebooks & Handhelds
- Portable instrumentation
- Digital cameras
- Peripherals



Maximum Ratings

Rating	Symbol	Value	Unit
Peak pulse current (tp=8/20µs)	I _{PP}	8	A
ESD voltage (Contact discharge)	V _{ESD}	±30	kV
ESD voltage (Air discharge)		±30	
Storage & operating temperature range	T _{STG} , T _J	-55~+150	°C

Electrical Characteristics (T_J=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V _{RWM}				12	V
Reverse breakdown voltage	V _{BR}	I _{BR} =1mA	13.3			V
Reverse leakage current	I _R	V _R =12V			1	μA
Clamping voltage (tp=8/20μs)	V _C	I _{PP} =1A		20		V
Clamping voltage (tp=8/20μs)	V _C	I _{PP} =8A		28		V
Off state junction capacitance	C _J	0Vdc,f=1MHz			55	pF

Typical Characteristics Curves

Figure 1. Power Derating Curve

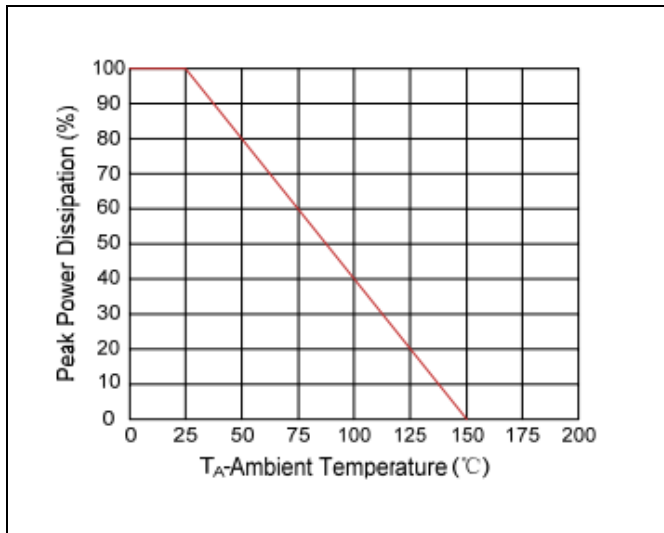


Figure 2. Pulse Waveform

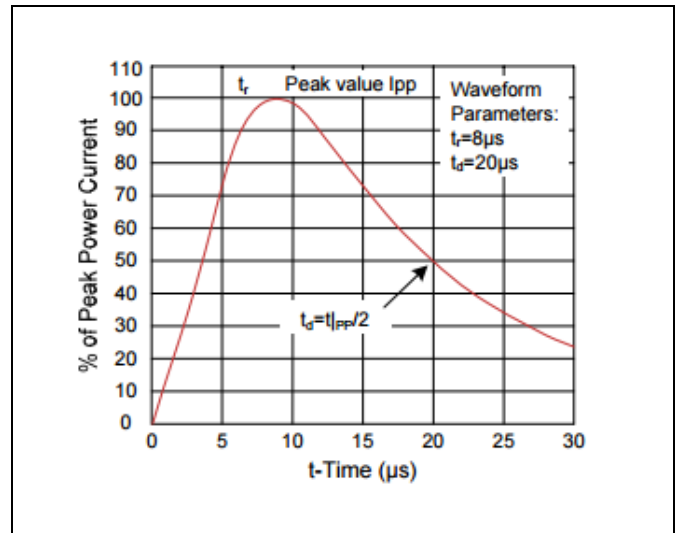


Figure 3. Capacitance vs. Reverse Voltage

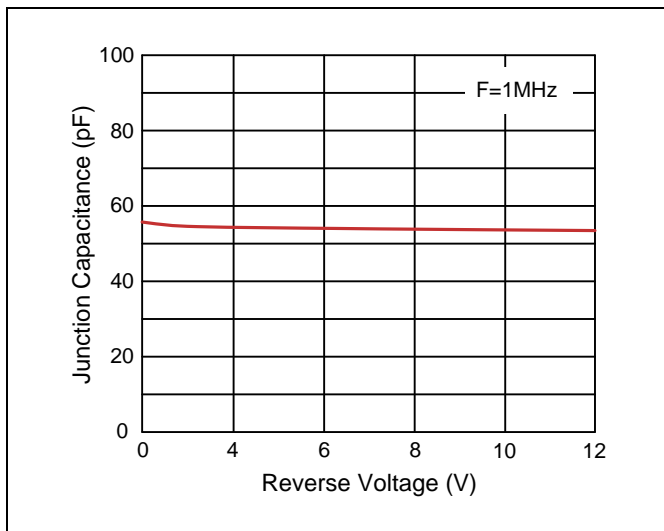
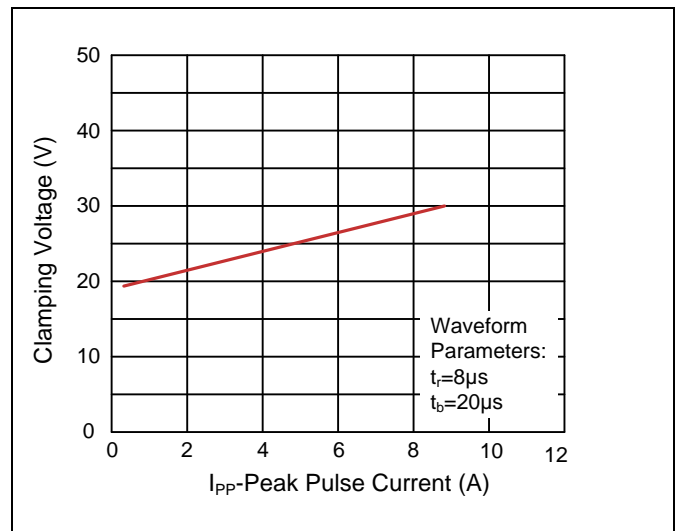
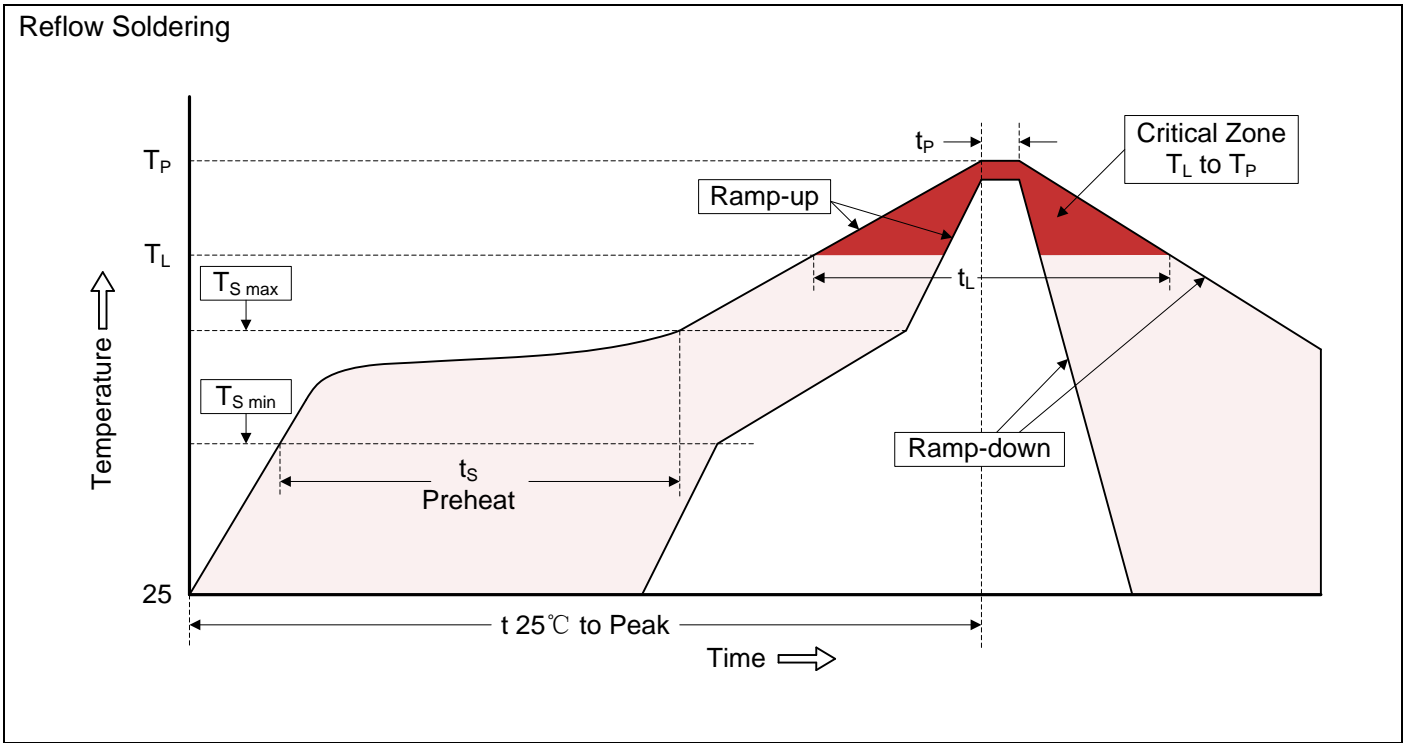


Figure 4. Clamping Voltage vs. Peak Pulse Current



Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat <ul style="list-style-type: none"> -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s) 	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L <ul style="list-style-type: none"> -Ramp-up Rate 	3°C/second max.
Time maintained above: <ul style="list-style-type: none"> -Temperature (T_L) -Time (t_L) 	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (SOD-523)

Symbol	Dimension (mm)			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.50	0.70	0.020	0.028
B	0.07	0.20	0.003	0.008
C	0.70	0.90	0.028	0.035
D	0.25	0.35	0.010	0.014
E	1.10	1.30	0.043	0.051
F	1.50	1.70	0.059	0.067
G	0.15	0.25	0.006	0.010

Packaging

Tape		Symbol	Dimension (mm)
		W	8.00±0.30
		P0	4.00±0.10
		P1	4.00±0.10
		P2	2.00±0.10
		D0	Φ1.55±0.10
		D1	Φ0.50±0.05
		E	1.75±0.10
		F	3.50±0.10
		A	1.00±0.10
		A0	0.50±0.10
		B	1.80±0.10
		B0	1.30±0.10
		K	0.65±0.10
		t	0.20±0.05
Reel		D	Φ178.0±2.0
		D2	Φ13.00.
		W1	9.50
		Quantity: 3000PCS	